

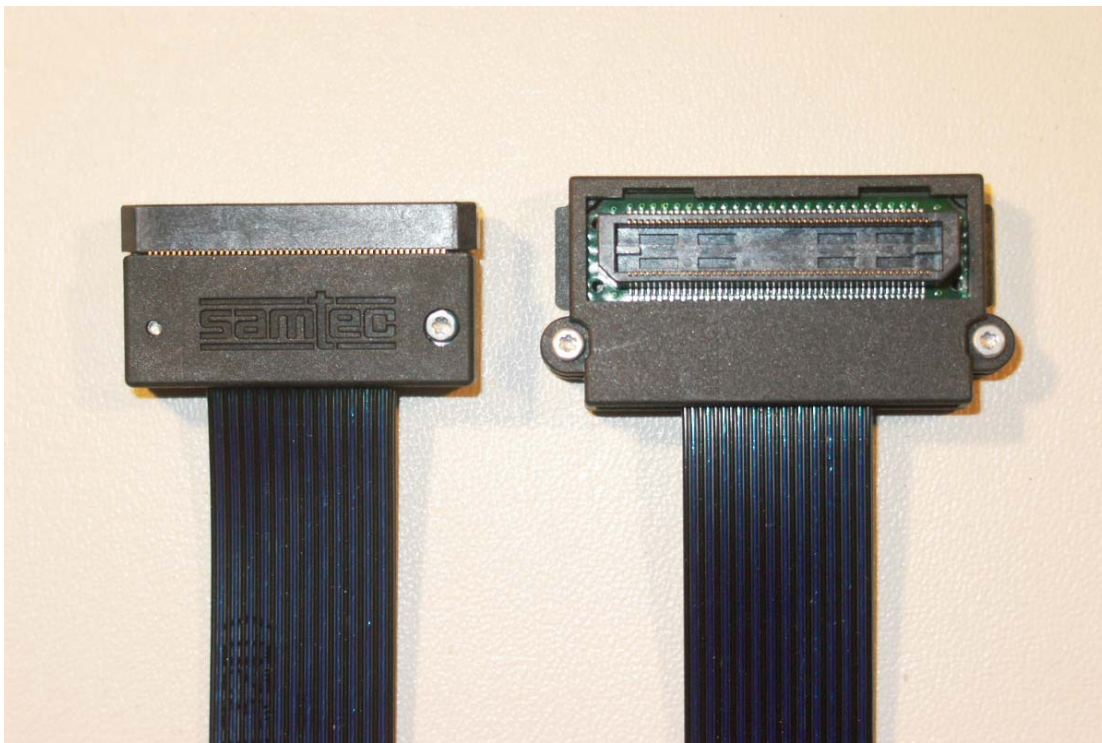


High Data Rate Characterization Report

HBCD-050-39.37-TEU-TED-1

HBCD-050-39.37-TTR-TBL-1

HBCD-050-39.37-TTR-TED-1



Mated with:
BSH-050-01-x-D-A

Description:
Cable Assembly, High Data Rate, 0.5mm Pitch

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

Table of Contents

<i>Introduction</i>	1
<i>Product Description</i>	1
<i>Results Summary</i>	3
Time Domain Data	3
Impedance	3
Timing Measurements	3
NEXT	4
FEXT	4
Frequency Domain Data	5
Insertion Loss	5
Return Loss	8
Near End Crosstalk	11
Far End Crosstalk	14
<i>Test Procedures</i>	17
Fixturing:	17
Time Domain Testing	19
Impedance:	19
Propagation Delay:	19
Skew:	19
NEXT and FEXT:	19
Frequency Domain Testing	20
Attenuation	20
Return Loss	20
Near and Far End Crosstalk	20
<i>Equipment</i>	21
Time Domain Testing	21

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

Introduction

This testing was performed to evaluate the electrical performance of the HBCD series of high-speed cable systems. Testing was performed in accordance to the High Performance Electrical Interconnect (HPEI) SFF-8416¹, Level 1, testing standards when applicable.

Time domain and frequency domain measurements were made. Time domain measurements included impedance, propagation delay, crosstalk and skew. Frequency domain measurements were performed using TDA's IConnect software (Version 3.0) and included insertion loss (IL), return loss (RL), near end crosstalk (NEXT) and far end crosstalk (FEXT). All measurements were made utilizing test boards specifically designed for this project and are referred to as "test board" in this report. The test boards were identified as "HBCD CABLE TEST BOARD PCB-100178-TEST REV-E".

Product Description

Each sample consists of two 39.37 inch (1m), 38 AWG micro-co-axial cables that contain 50 single lines. At each end of the cable there is a connector that is terminated to a small transition PCB. The respective connector is soldered to the PCB. All cable assemblies are terminated with a BTH micro header at both ends. There are two types of BTH connectors that can be terminated; edge-mount (EM) or vertical mount (DV). The cable connectors contain 50 pins per row.

The connectors are soldered to the transition PCBs. The green transition boards are a straight through type that connects the outer connector row of one connector to the outer row of the opposite connector and the inner connector row is connected to the inner row on the other connector. The red transition boards are crossover type boards and are used to connect the inner connector row to the out connector row and visa versa. The crossover boards are used here to achieve a position 1 to position 1 mapping, because the second end terminations are turned down for the edge mount and turned left for the vertical mount. Figure 1 on the preceding page is a picture of a termination configuration of one of the test samples. The board/cable termination areas are covered with plastic caps

Three samples, one of each type of termination configuration, were tested. The actual sample part numbers tested are shown in below in Table 1, which also identifies End 1 and

¹ Measurement and Performance Requirements for HPEI Bulk Cable, Rev 14, March 25, 2004

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

End 2 of each assembly. Two lines, the longest and the shortest electrical paths, from each sample were tested

Length	Part Number	Termination	End 1	End 2
39.37in	HBCD-050-39.37-TEU-TED-1	EM-EM	TEU	TED
39.37in	HBCD-050-39.37-TTR-TBL-1	DV-DV	TTR	TBL
39.37in	HBCD-050-39.37-TTR-TED-1	DV-EM	TTR	TED

Table 1: Sample Descriptions

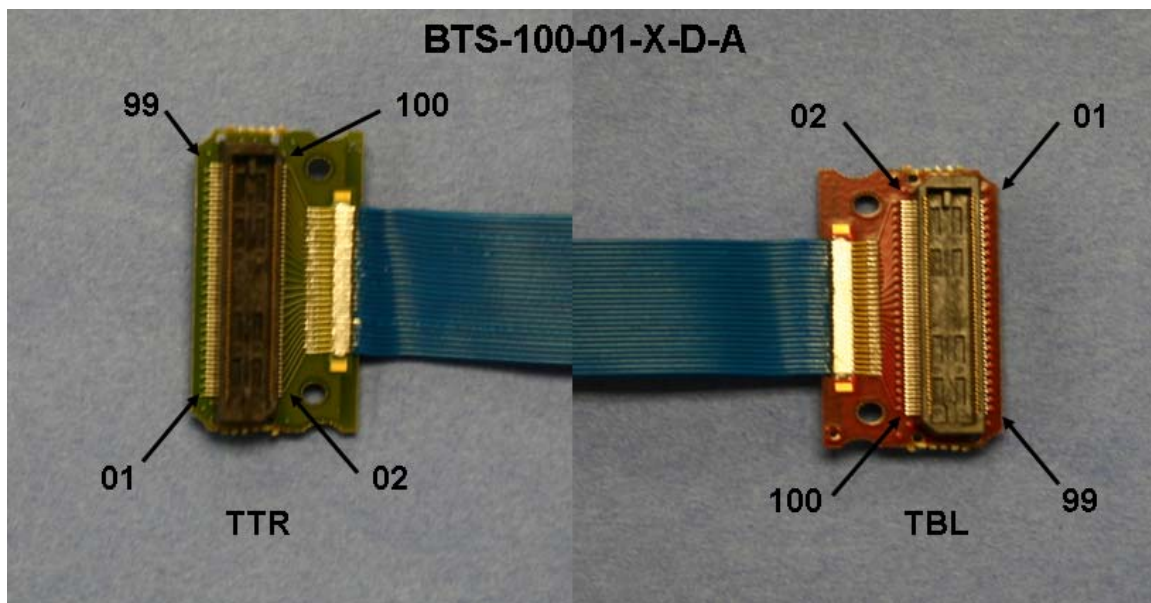


Figure 1: Test Sample Configuration, Part #: HBCD-39.37-TTR-TBL-1

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

Results Summary

Time Domain Data

Impedance

Impedance measurements were performed using a filtered risetime of 100 pS.

Note that all measurements were performed with the cable assembly mated to the respective connector/test board. Data was measured at the cable termination and 200 pS into the cable.

Assembly	Path	End Option				Cable	
		End 1		End 2		End 1	End 2
		Z _{Min} (Ω)	Z _{Max} (Ω)	Z _{Min} (Ω)	Z _{Max} (Ω)	Z _{max} (Ω)	Z _{max} (Ω)
TEU-TED	Long	46.5	58.9	46.7	61.0	49.5	50.0
	Short	46.7	61.5	45.7	63.1	49.9	51.8
TTR-TBL	Long	46.2	64.2	45.8	64.4	48.9	49.2
	Short	47.0	58.6	46.0	59.7	49.4	49.2
TTR-TED	Long	46.4	64.1	46.6	60.8	49.1	49.2
	Short	46.7	58.2	45.5	64.0	49.3	51.1

Table 2: Impedance Measurements

Timing Measurements

Skew was calculated as the difference between the propagation delay of the longest (outer row) and the shortest (inner Row) electrical paths. End 1 of each assembly was the source end for these measurements. The results are tabulated below.

Assembly	Path	Propagation Delay (nS)	Skew (nS)
TEU-TED	Long	5.044	0.009
	Short	5.053	
TTR-TBL	Long	5.121	0.006
	Short	5.015	
TTR-TED	Long	5.088	0.055
	Short	5.033	

Table 3: Timing Measurements

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

NEXT

The near end crosstalk was measured in the time domain and converted to a percentage and reported below in Table 3. The incident pulse amplitude from the TDR was 244 mV. The acquired data was measured using a filtered rise time of 100 pS. The End 1 and End 2 headings in Table 4 represent the near-end cable assembly connector, i.e. the source end. All NEXT measurements were performed with the cable assembly mated to the respective connector/test board. Since most of the crosstalk occurs in the connectors, the values in Table 3 represent the crosstalk that occurs in the near-end mated cable assembly and the test board connectors.

Assembly	Path	END1		END 2	
		NEXT (mV)	NEXT (%)	NEXT (mV)	NEXT (%)
TEU-TED	Long	12.4	5.1	16.0	6.6
	Short	14.0	5.7	21.6	8.9
TTR-TBL	Long	7.2	3.0	10.8	4.4
	Short	5.8	2.4	8.2	3.4
TTR-TED	Long	7.2	3.0	16.2	6.6
	Short	5.4	2.2	21.0	8.6

Table 4: % NEXT

FEXT

The far end crosstalk was measured in the time domain and converted to a percentage and reported below in Table 4. The incident pulse amplitude from the TDR was 244 mV. The acquired data was measured using a filtered rise time of 100 pS. The End 1 and End 2 headings in Table 4 represent the near-end cable assembly connector, i.e. the source end. All FEXT measurements were performed with the cable assembly mated to the respective connector/test board. The values in Table 4 represent the crosstalk measured at the far end of the assembly.

Assembly	Path	END 1		END 2	
		FEXT (mV)	FEXT (%)	FEXT (mV)	FEXT (%)
TEU-TED	Long	18.8	7.7	18.8	7.7
	Short	18.4	7.5	18.4	7.5
TTR-TBL	Long	11.6	4.8	11.6	4.8
	Short	9.2	3.8	9.2	3.8
TTR-TED	Long	16.4	6.7	16.0	6.6
	Short	16.4	6.7	16.8	6.9

Table 5: % FEXT

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

Frequency Domain Data

Insertion Loss

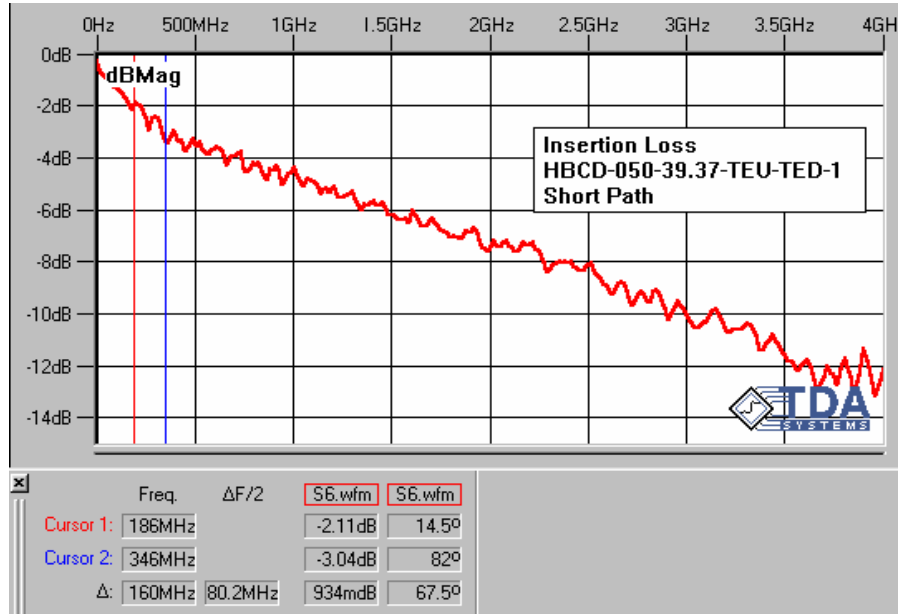


Figure 2: HBCD-050-39.37-TEU-TED-1 Insertion Loss Short Path

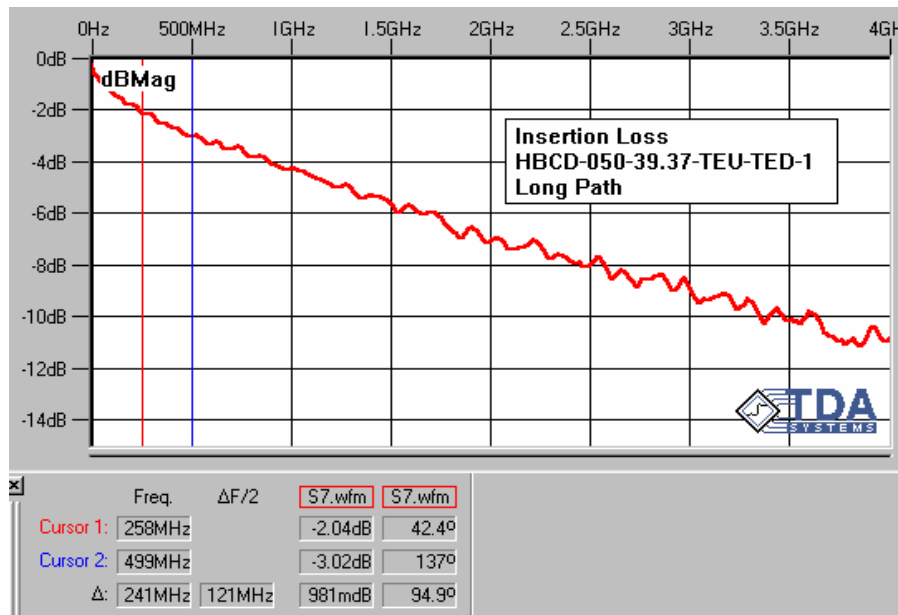


Figure 3: HBCD-050-39.37-TEU-TED-1 Insertion Loss Long Path

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

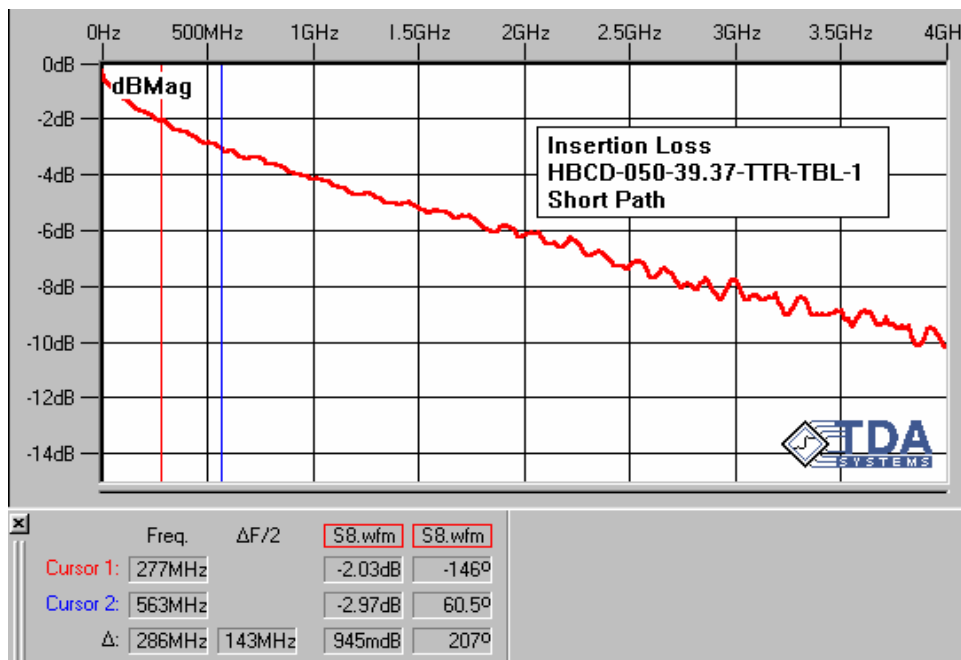


Figure 4: HBCD-050-39.37-TTR-TBL-1 Insertion Loss Short Path

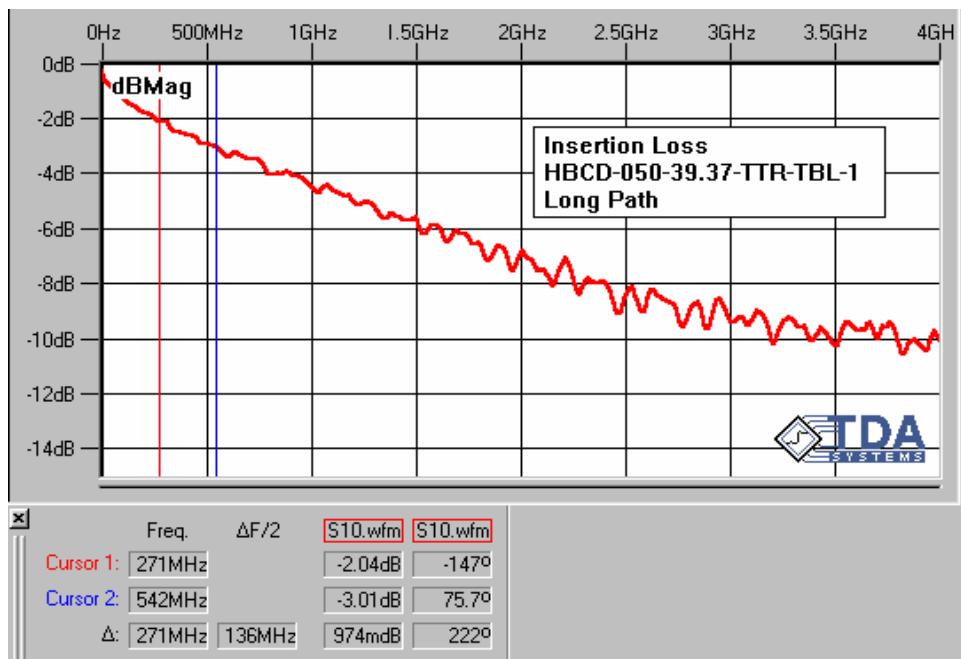


Figure 5: HBCD-050-39.37-TTR-TBL-1 Insertion Loss Long Path

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

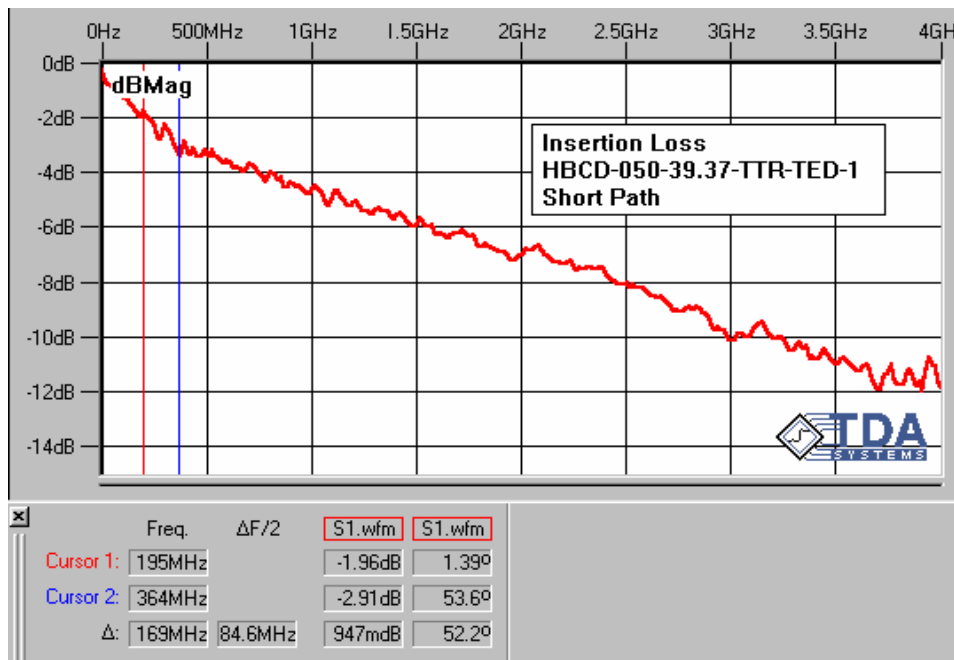


Figure 6: HBCD-050-39.37-TTR-TED-1 Insertion Loss Short Path

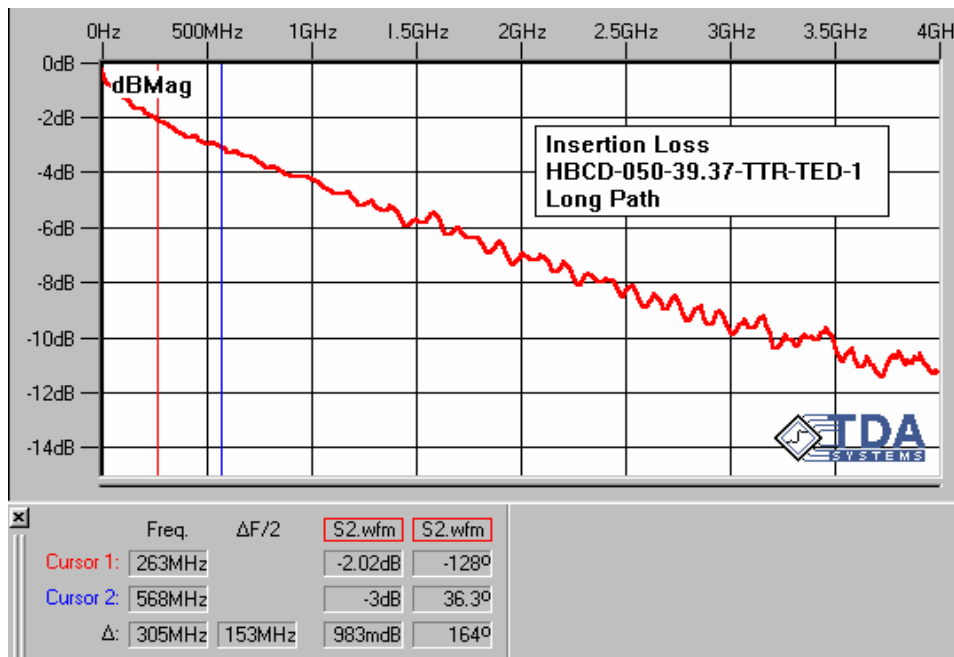


Figure 7: HBCD-050-39.37-TTR-TED-1 Insertion Loss Long Path

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

Return Loss

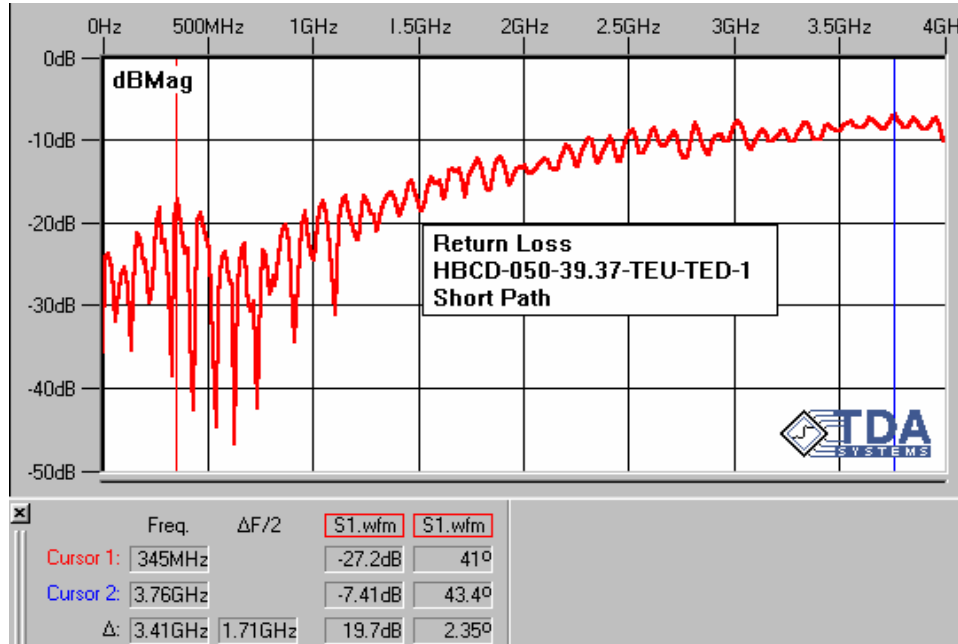


Figure 8: HBCD-050-39.37-TEU-TED-1 Return Loss Short Path

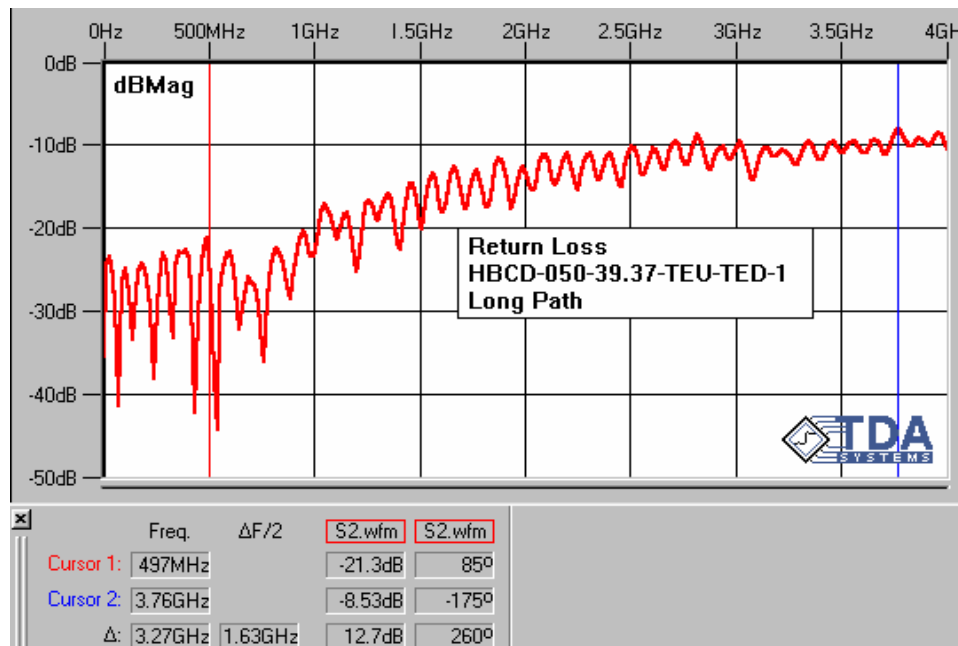


Figure 9: HBCD-050-39.37-TEU-TED-1 Return Loss Long Path

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

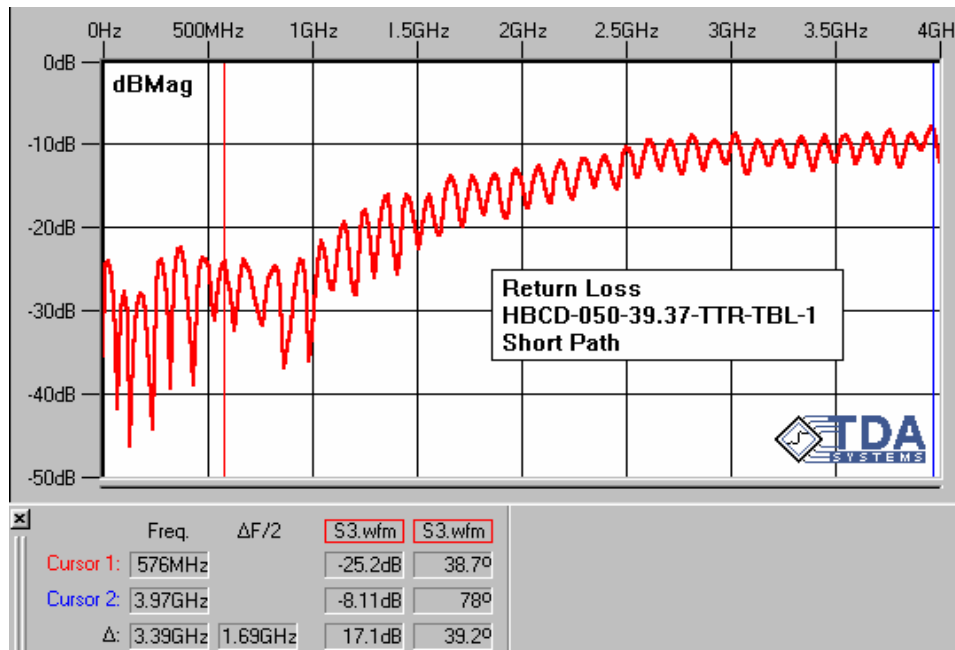


Figure 10: HBCD-050-39.37-TTR-TBL-1 Return Loss Short Path

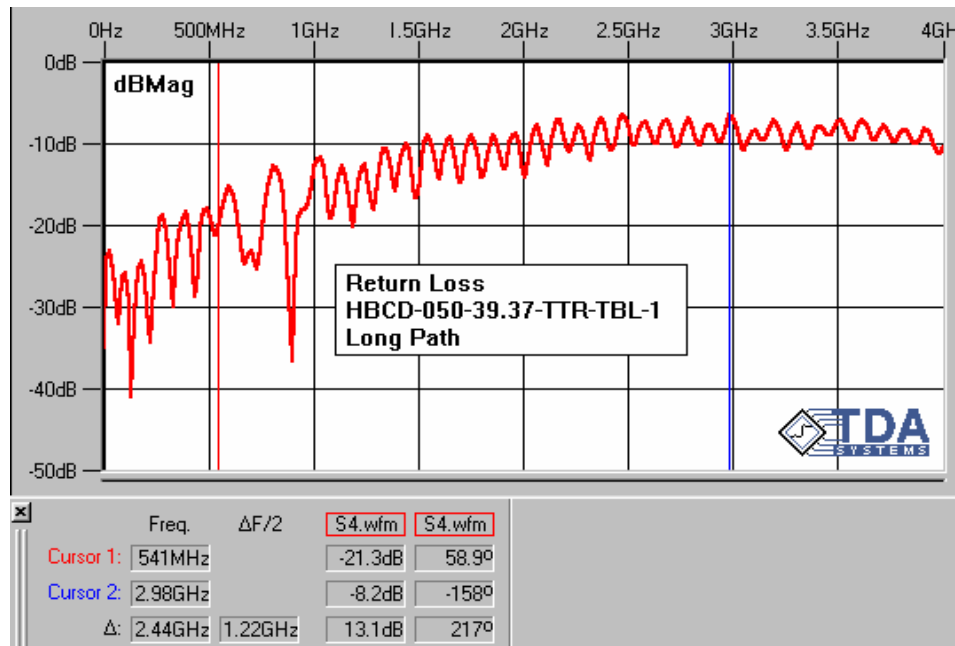


Figure 11: HBCD-050-39.37-TTR-TBL-1 Return Loss Long Path

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

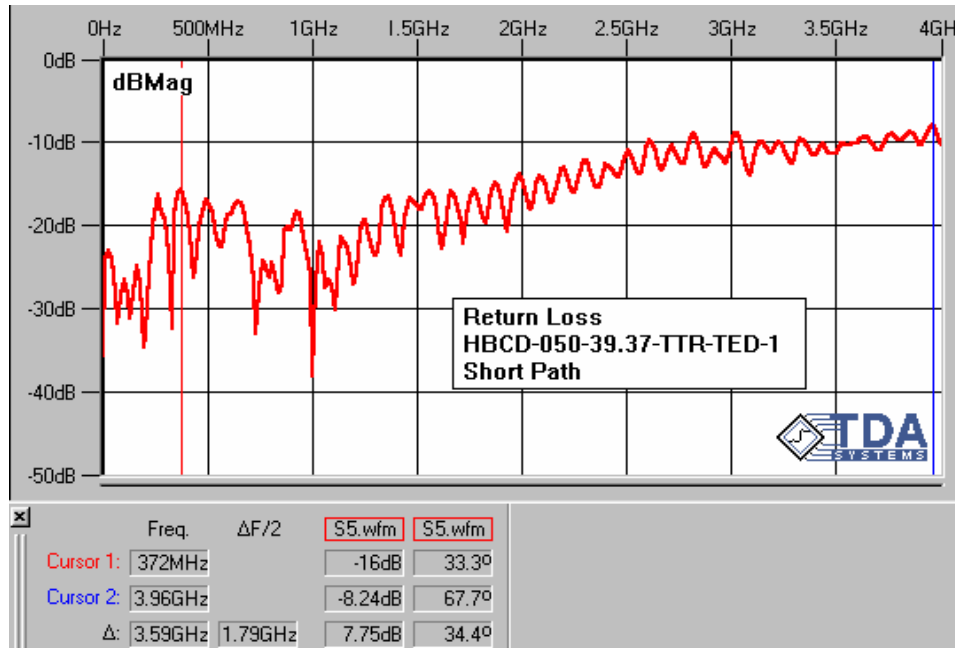


Figure 12: HBCD-050-39.37-TTR-TED-1 Return Loss Short Path

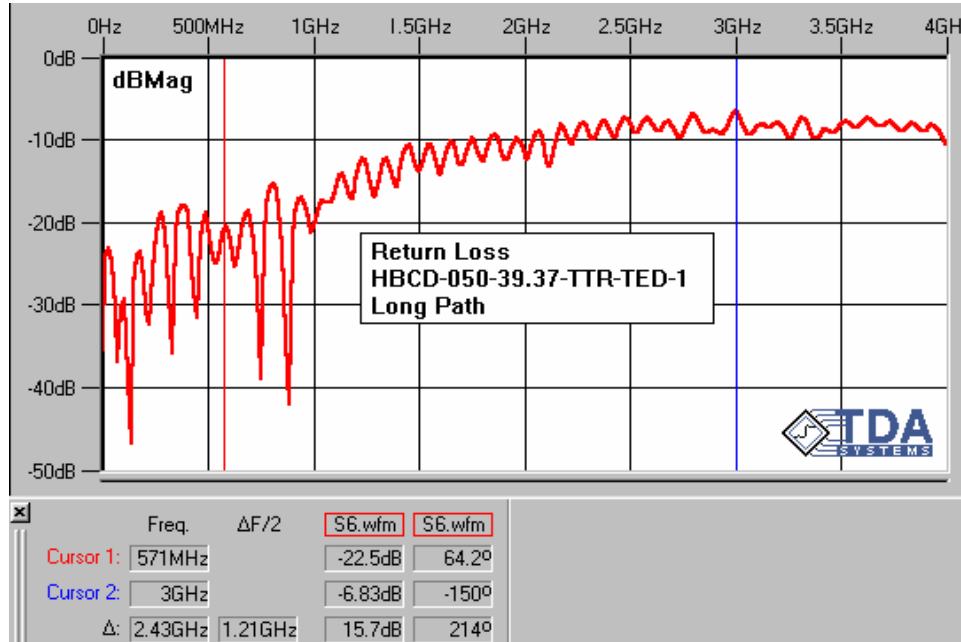


Figure 13: HBCD-050-39.37-TTR-TED-1 Return Loss Long Path

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

Near End Crosstalk

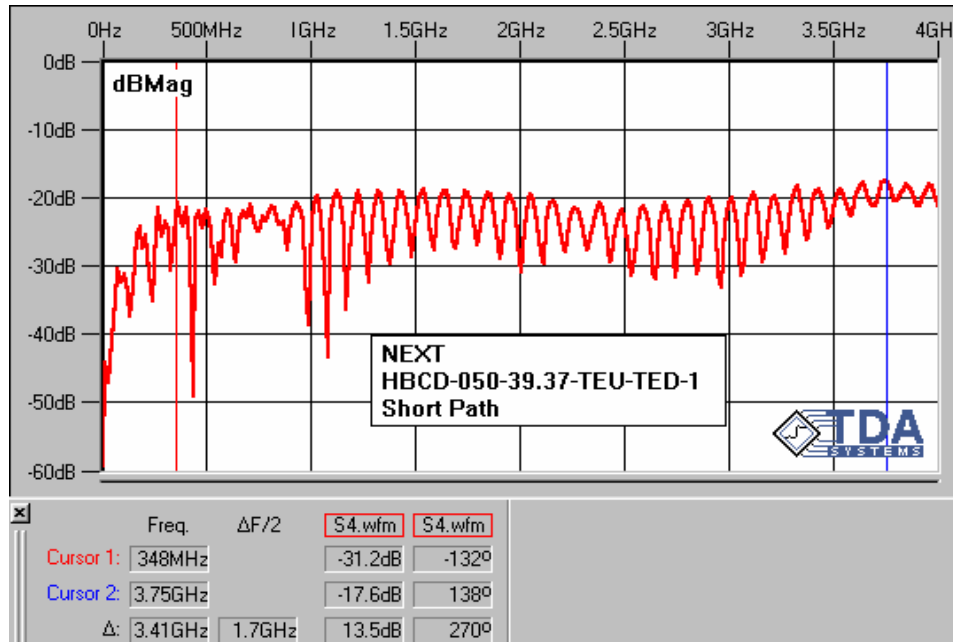


Figure 14: HBCD-050-39.37-TEU-TED-1 NEXT Short Path

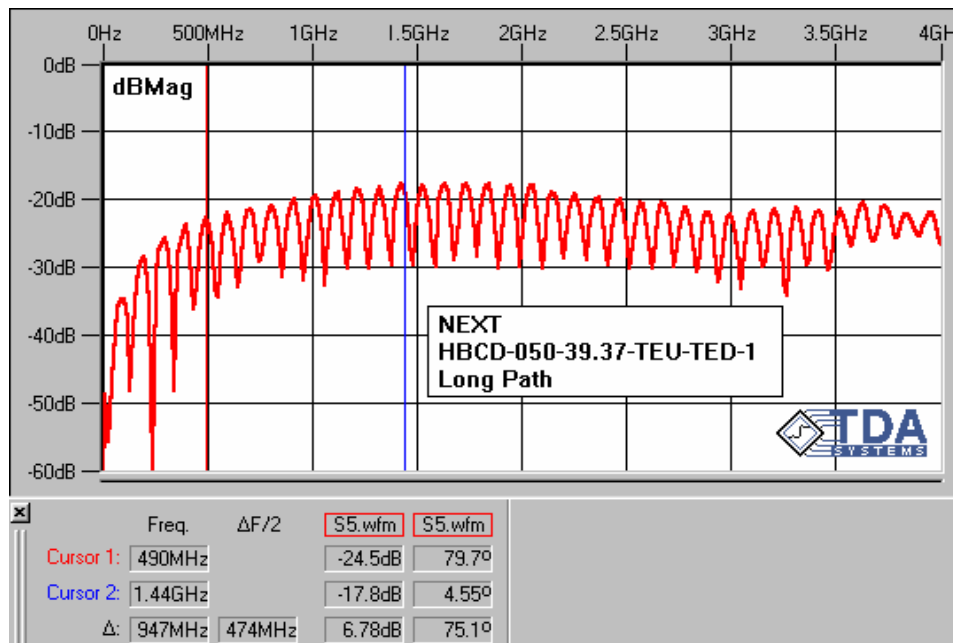


Figure 15: HBCD-050-39.37-TEU-TED-1 NEXT Long Path

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

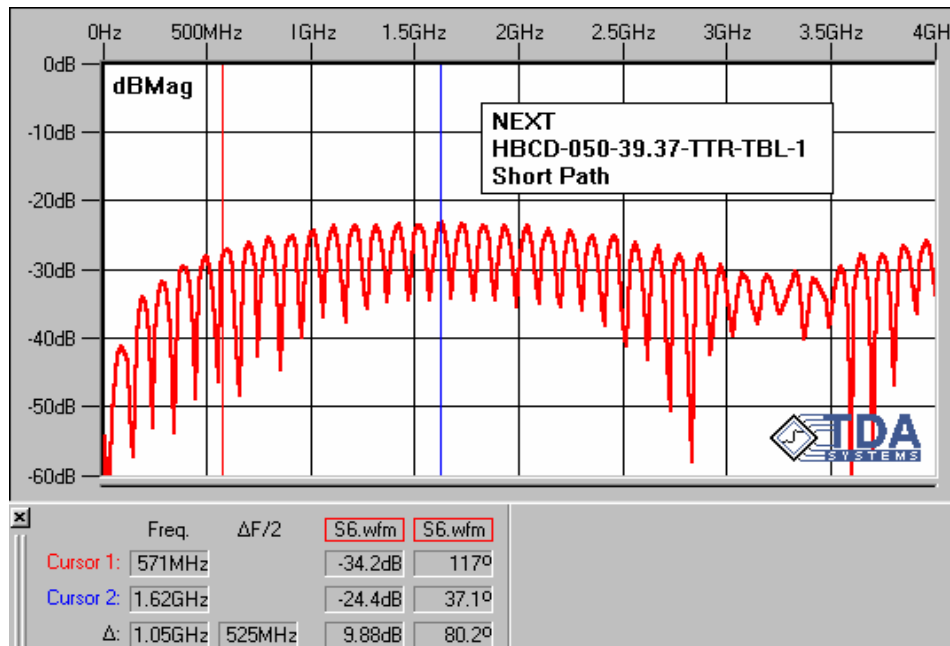


Figure 16: HBCD-050-39.37-TTR-TBL-1 NEXT Short Path

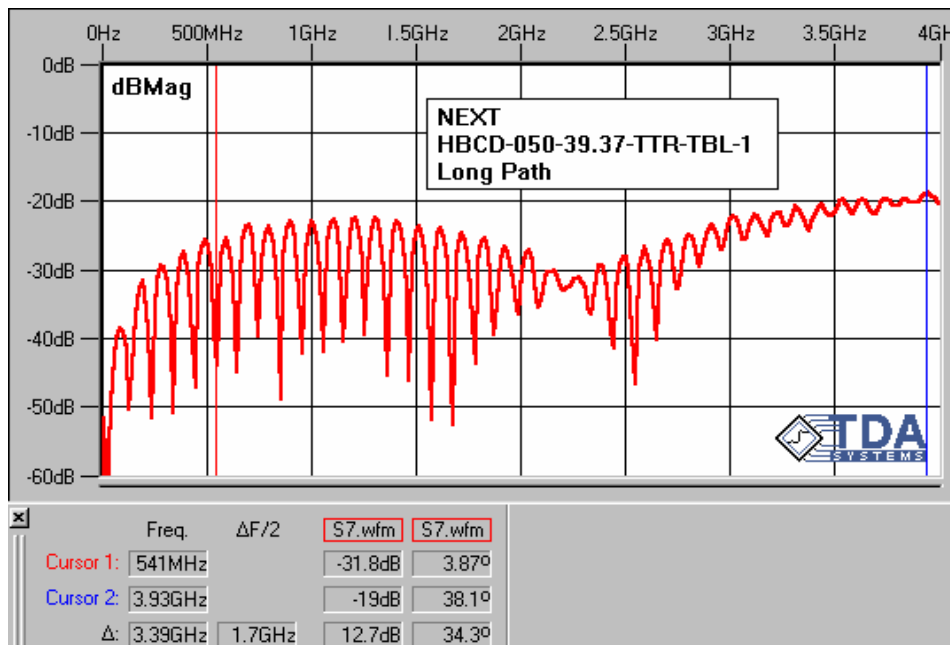


Figure 17: HBCD-050-39.37-TTR-TBL-1 NEXT Long Path

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

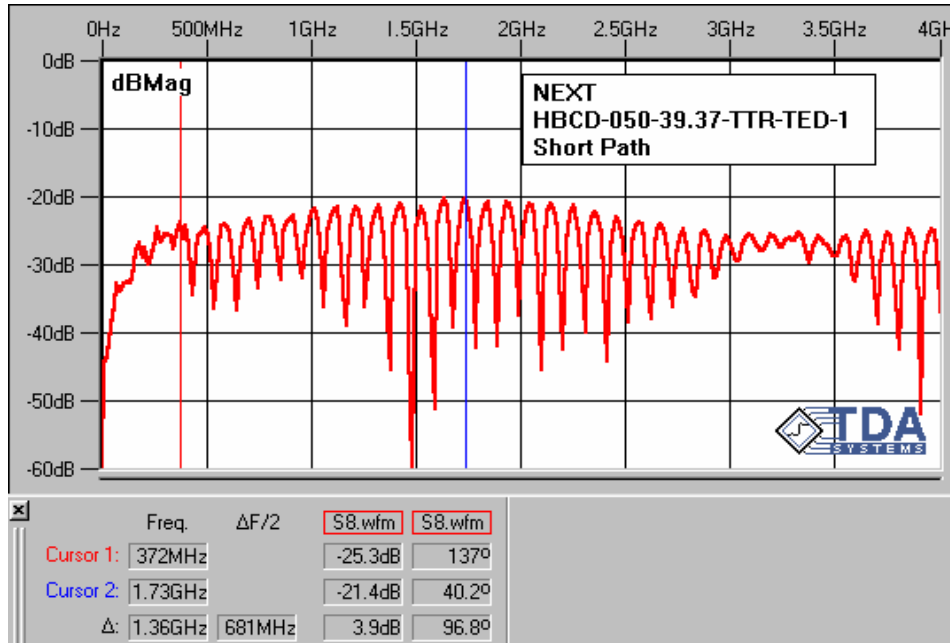


Figure 18: HBCD-050-39.37-TTR-TED-1 NEXT Short Path

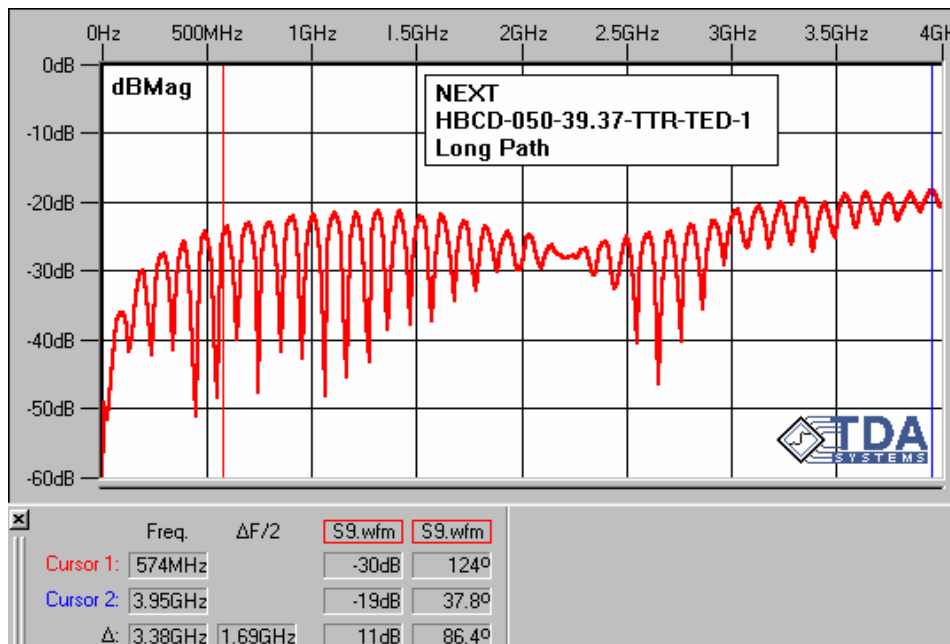


Figure 19: HBCD-050-39.37-TTR-TED-1 NEXT Long Path

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

Far End Crosstalk

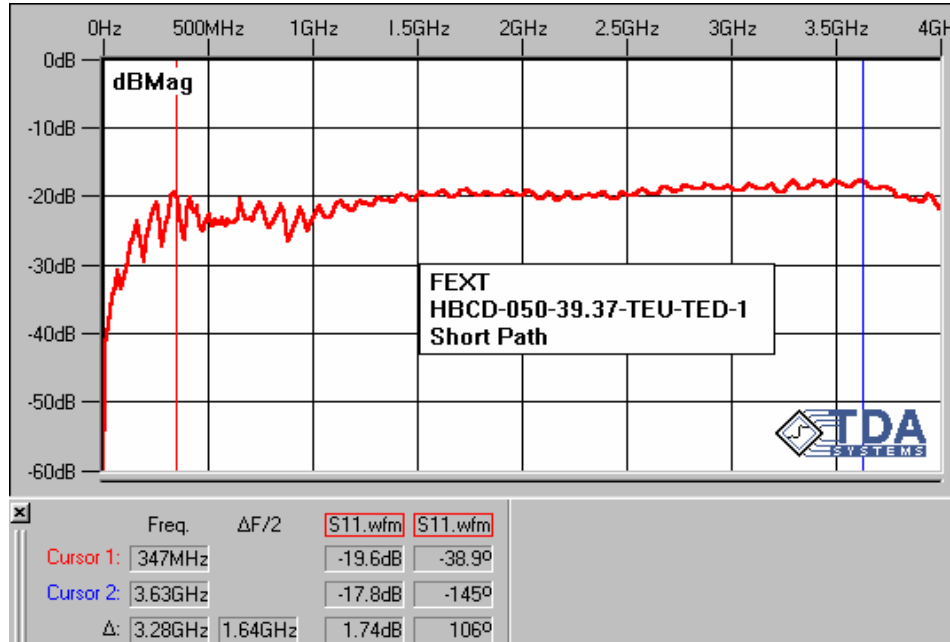


Figure 20: HBCD-050-39.37-TEU-TED-1 FEXT Short Path

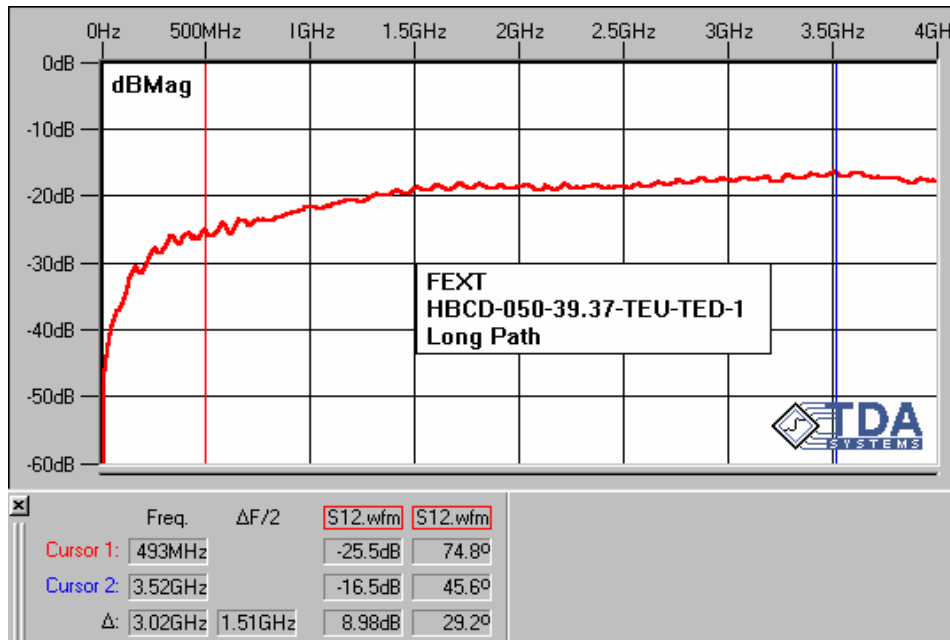


Figure 21: HBCD-050-39.37-TEU-TED-1 FEXT Long Path

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

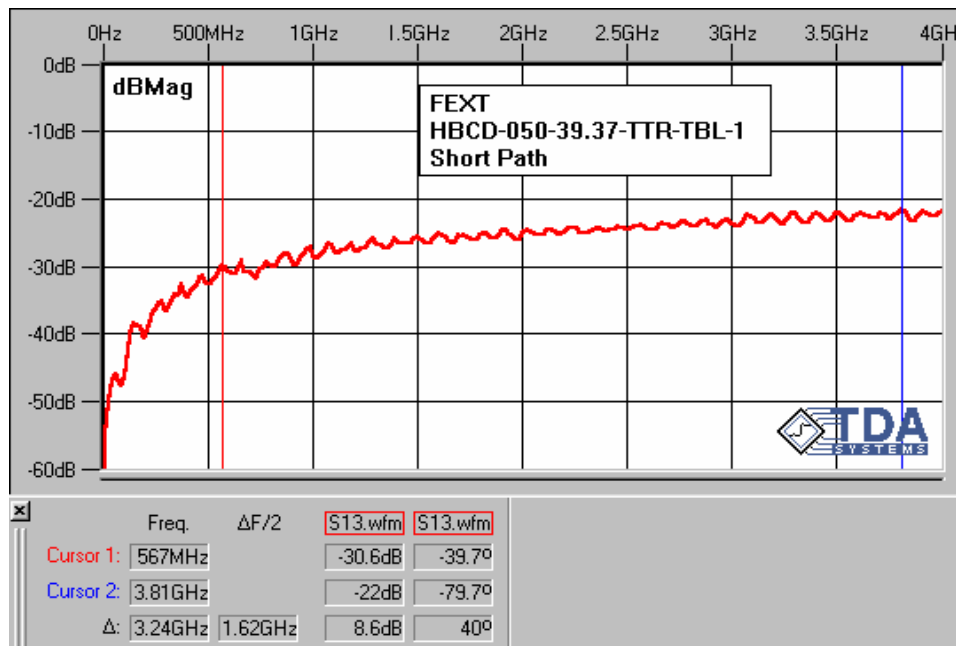


Figure 22: HBCD-050-39.37-TTR-TBL-1 FEXT Short Path

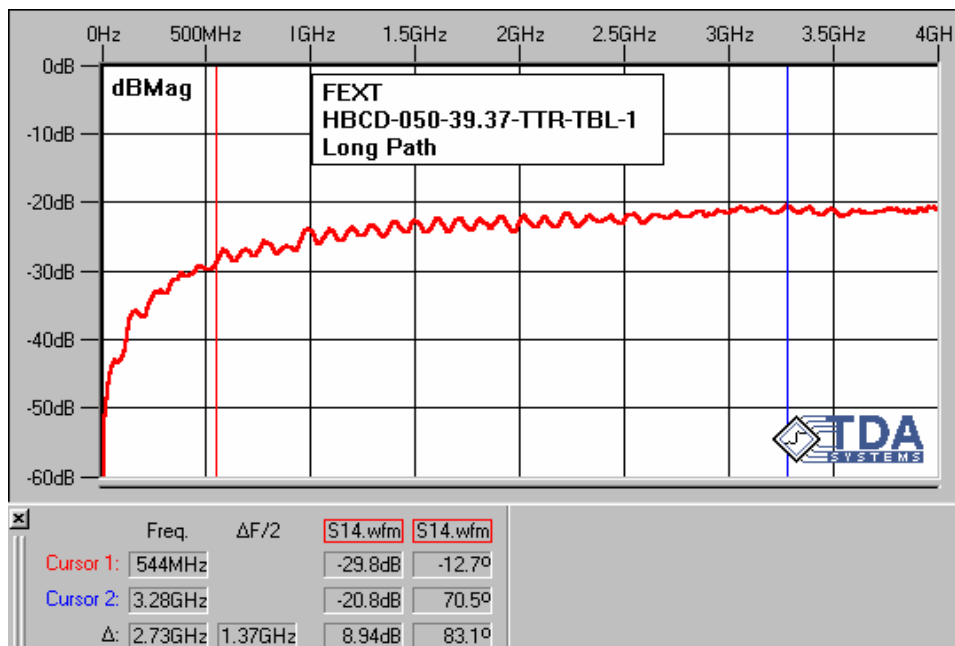


Figure 23: HBCD-050-39.37-TTR-TBL-1 FEXT Long Path

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

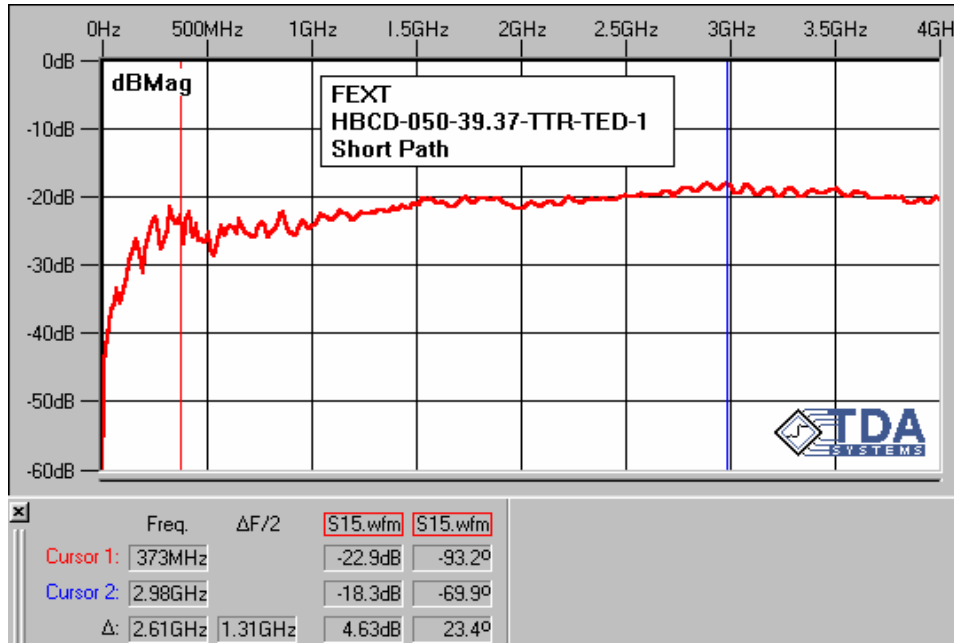


Figure 24: HBCD-050-39.37-TTR-TED-1 FEXT Short Path

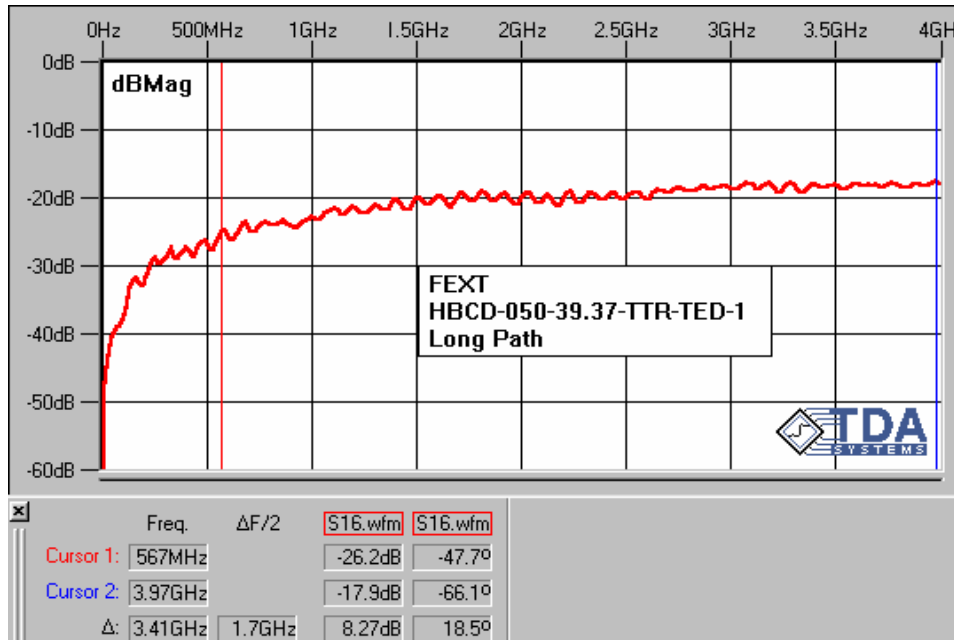


Figure 25: HBCD-050-39.37-TTR-TED-1 FEXT Long Path

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

Test Procedures

Fixturing:

All measurements were performed using the test boards specifically designed for this project. The test boards have trace lengths of 1.205 inches and provide for the interconnection to the HBCD cable by use of replaceable SMA connectors. Each test board has a THRU reference trace and an OPEN reference traces. Figure 26 below shows how the THRU reference trace was utilized to compensate for the losses due to the coaxial test cables, SMA launches, and the test board traces during testing.

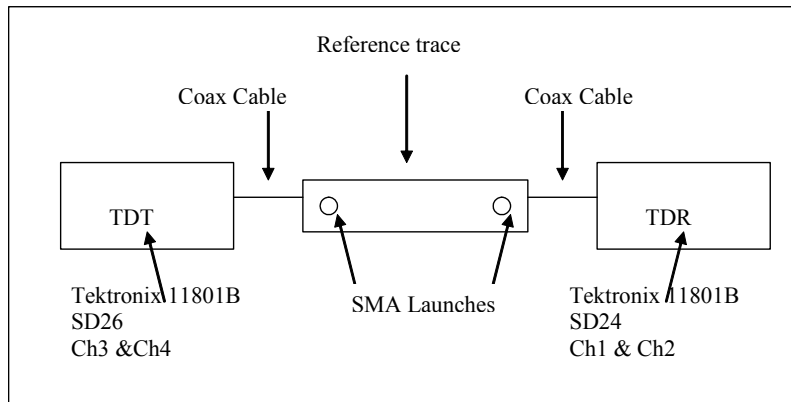


Figure 26: Test setup for Thru Reference Acquisition

Measurements were then performed using the test boards as shown in Figure 27. A picture of the test board and cable is shown in Figure 28 on the following page.

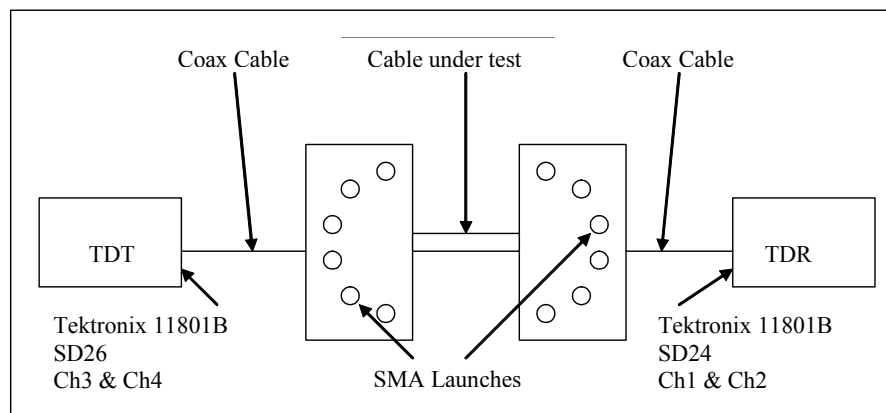


Figure 27: Characterization test setup

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

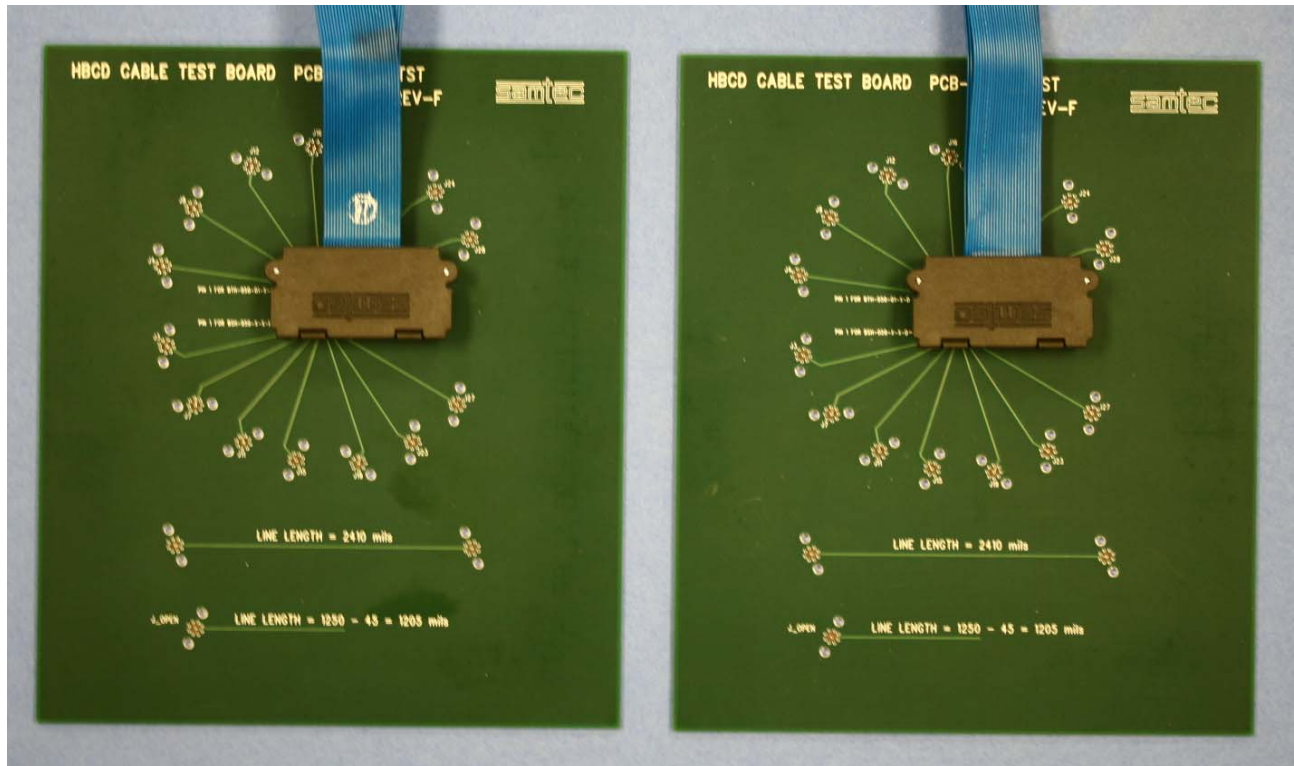


Figure 28: Test setup with Test PCBs and HBCD cable.

The cable termination uses a S, G, S, G ... configuration. The respective signal line numbers are shown in Table 6 below (first 25 positions shown; there are a total of 50 positions per row). All adjacent lines are terminated where applicable.

1	G	5	G	9	G	13	G	17	G	21	G	25	G	29	G	33	G	37	G	41	G	45	G	49
2	G	6	G	10	G	14	G	18	G	22	G	26	G	30	G	34	G	38	G	42	G	46	G	50

Table 6: Grounding schemes and respective signal line number

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

Time Domain Testing

Impedance:

The Tektronix 11801B oscilloscope was set up in TDR (time domain reflectometry) mode using a 100 pS filtered risetime and 16 averages. The horizontal setup of the TDR used a record length of 512-points, and a horizontal scale of 200ps/div; allowing for the near-end connector and a portion of the cable to be displayed. All impedance measurements were made at the near-end cable termination and 200 pS into the cable.

Propagation Delay:

The propagation delay was measured and skew calculated by first acquiring a thru reference pulse of the reference board. Using the delay function of the TDR, set at 50% amplitude of the reference pulse, the sample was inserted and the sample delay was measured. The TDR delay function calculates the sample delay by subtracting the delay measurement of the reference pulse from the delay measurement of the sample plus the test board traces.

Skew:

Skew is defined as the difference between of the propagation delays of the longest (maximum delay) and the shortest (minimum delay) electrical paths.

NEXT and FEXT:

Near end crosstalk (NEXT) and far end crosstalk (FEXT) measurements were made using the Tektronix 11801B oscilloscope. A thru reference of the coaxial test cables, SMAs, and reference board was performed to determine the pulse amplitude of the TDR generator (see Figure 26).

To acquire NEXT, a signal was applied using the oscilloscope pulse generator. NEXT was measured on an adjacent signal line at the near end (see Figure 29). To acquire FEXT, a trace was driven with the oscilloscope pulse generator. FEXT was measured on an adjacent trace at the far end (see Figure 30). All adjacent lines were terminated, at both ends, with 50Ω SMA loads; refer to Figures 29 and 30.

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

Frequency Domain Testing

All frequency domain measurements were made using the Tektronix 11801B oscilloscope. Testing was performed using a risetime of 35 pS. The horizontal scale was set to 5 nS/div, the record length was set to 5120 points and the number of averages was set to 128. These values were selected to ensure the ratio between the number of points and the window length was long enough to capture the highest frequencies and still yield a small enough frequency step to gain adequate resolution. End 1 of each assembly was the source end for all frequency domain measurements. All adjacent lines were terminated, at both ends, with 50 Ω SMA loads; refer to Figures 29 and 30.

Attenuation:

Insertion Loss test setup losses were compensated for by acquiring a thru measurement (reference output pulse) of the coaxial test cables, SMAs, and the reference board (see Figure 26). A thru measurement of an assembly was taken and then post processed by using TDA Systems' IConnect software (Version 3.0). The result is the insertion loss of the cable assembly.

Return Loss:

An open circuit reference measurement was taken using the J_OPEN reference line on the test board. A matched reflection waveform of the cable assembly, i.e. with the cable assembly terminated in a 50- Ω SMA load on the far end test board, was acquired and then post processed by using TDA Systems' IConnect software (Version 3.0). The result is the return loss of the cable assembly.

Near and Far End Crosstalk:

NEXT and FEXT were measured in the time domain using the oscilloscope and then converted to frequency domain data using TDA Systems' IConnect software (Version 3.0). Initially a thru reference measurement of the coaxial test cables, SMAs, and reference board was performed to compensate for the test setup losses (see Figure 26).

To acquire NEXT a trace was driven using the oscilloscope pulse generator. NEXT was measured, in the time domain, on an adjacent trace (see Figure 29). NEXT was then post processed using TDA Systems' IConnect software to generate the NEXT of the cable assembly in the frequency domain.

To acquire FEXT a trace was driven using the oscilloscope pulse generator. FEXT was measured, in the time domain, on an adjacent trace at the far end (see Figure 30). FEXT

Series: HBCD

Description: Cable Assembly, High Data Rate, 0.5mm Pitch

was then post processed using TDA Systems' IConnect software to generate the FEXT of the cable assembly in the frequency domain.

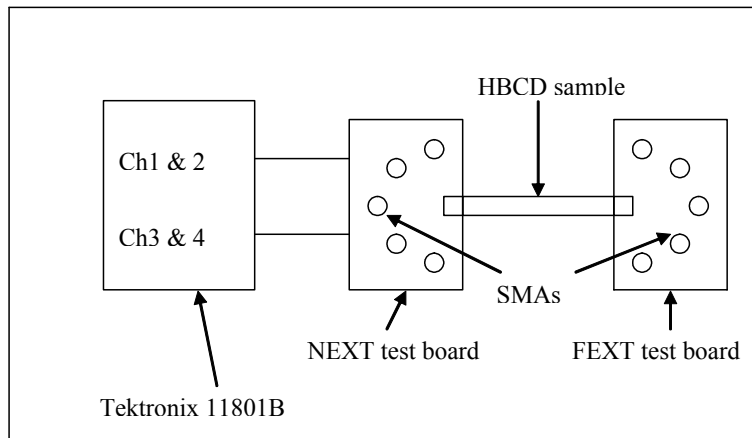


Figure 29: NEXT Measurement Setup.

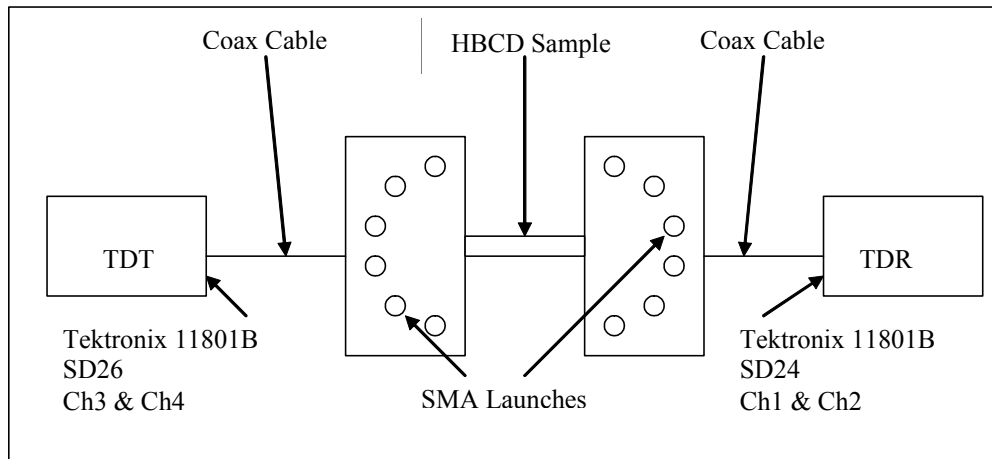


Figure 30: FEXT Measurement Setup

Equipment

Time Domain Testing

Tektronix 11801B Oscilloscope
 Tektronix SD26 Sampling Head
 Tektronix SD24 TDR/Sampling Head